iC-LSB 8-CHANNEL ACTIVE PHOTOSENSOR ARRAY



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FEATURES

Monolithic array of independent photosensors with excellent matching Compact photosensor size of 800 µm x 300 µm enabling high-quality encoder scanning at reduced system dimensions Narrow track pitch of 0.42 mm cuts down illumination efforts Enhanced EMI immunity due to on-chip pre-amplification Dark current compensation permits high temperature operation Open-collector outputs as highside current source Simple gain setting and current-to-voltage conversion by external load resistors Single supply operation from 4 V to 5.5 V Low power consumption

Space saving, RoHS compliant optoQFN and optoBGA packages

Options: extended temperature range of -40 to 125 $^{\circ}\text{C},$ customized COB modules, reticles and code discs

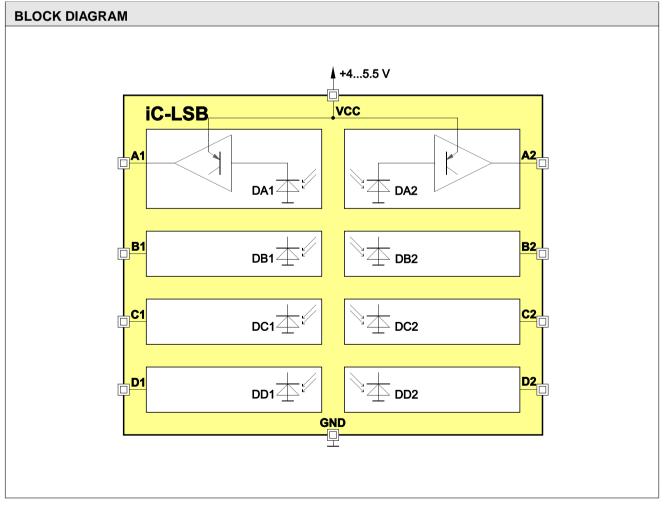
APPLICATIONS

Optical position encoding from analog sine/cosine signals Incremental encoders with index signal

PACKAGES



14-pin optoBGA 6.2 mm x 5.2 mm



iC-LSB 8-CHANNEL ACTIVE PHOTOSENSOR ARRAY



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DESCRIPTION

The iC-LSB sensor array, coming with 8 independent channels, is a general purpose optoelectronic scanner made to suit a variety of encoding applications, such as rotary and linear encoders used for motion control, robotics, power tools etc.

The sensor array features monolithically integrated photosensors with active areas of 800 μ m x 300 μ m each in combination with fast on-chip photocurrent amplifiers, enabling an analog output at reasonable signal strength to the circuit board.

The highside current source output construction

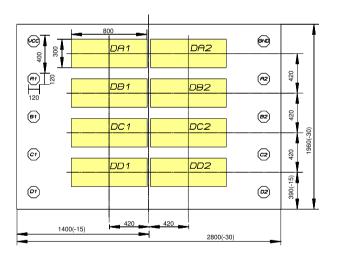
avoids a ground referenced signal and permits the subsequent electronics to adjust the gain. In its simplest form this is done by load resistors, for instance.

The spectral sensitivity range includes visible to near infrared light, with the maximum sensitivity being close to a wavelength of 700 nm.

Output currents of up to 50 μ A are supplied under low light conditions, for instance when illuminated at only 3μ W/mm² by an 850 nm LED. The photocurrent gain is 46 dB typically.

PACKAGES

PAD LAYOUT Chip size 2.80 mm x 1.96 mm



PAD FUNCTIONS No. Name Function

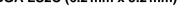
- 1 VCC +4...5.5 V Supply Voltage
- 2 A1 Highside Current Source Output
- 3 B1 Highside Current Source Output
- 4 C1 Highside Current Source Output
- 5 D1 Highside Current Source Output
- 6 D2 Highside Current Source Output
- 7 C2 Highside Current Source Output
- 8 B2 Highside Current Source Output
- 9 A2 Highside Current Source Output
- 10 GND Ground

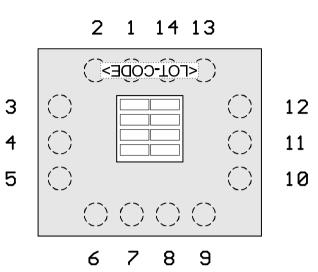
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PIN CONFIGURATION oBGA LS2C (6.2 mm x 5.2 mm)





PIN FUNCTIONS No. Name Function

1 VCC +4...5.5 V Supply Voltage Highside Current Source Output 2 A1 Highside Current Source Output 3 B1 Highside Current Source Output 4 C1 5 D1 Highside Current Source Output 6...9 n.c. Highside Current Source Output 10 D2 11 C2 Highside Current Source Output Highside Current Source Output 12 B2 13 A2 Highside Current Source Output 14 GND Ground

Pin numbers marked n.c. are not in use. For dimensional specifications refer to the relevant package data sheets, available separately. IC top markings, such as <LOT CODE>, indicate the orientation of the device.



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ABSOLUTE MAXIMUM RATINGS

These ratings do not imply operating conditions; functional operation is not guaranteed. Beyond these ratings device damage may occur.

ltem	Symbol	Parameter	Conditions			Unit
No.				Min.	Max.	
G001	VCC	Voltage at VCC		-0.3	6	V
G002	I(VCC)	Current in VCC		-20	20	mA
G003	V()	Pin Voltage, all signal outputs		-0.3	VCC+0.3	V
G004	I()	Pin Current, all signal outputs		-20	20	mA
G005	Vd()	ESD Susceptibility, all pins	HBM, 100 pF discharged through $1.5 k\Omega$		2	kV
G006	Tj	Junction Temperature		-40	150	°C
G007	Ts	Chip Storage Temperature		-40	150	°C

THERMAL DATA

ltem	Symbol	Parameter	Conditions				Unit
No.				Min.	Тур.	Max.	
T01	Та	Operating Ambient Temperature Range	package oBGA LS2C	-20		90	°C
			(extended temperature range on request)				
T02	Ts	Storage Temperature Range	package oBGA LS2C	-30		110	°C
T03	Tpk	Soldering Peak Temperature	package oBGA LS2C				
			tpk < 20 s, convection reflow tpk < 20 s, vapor phase soldering TOL (time on label) 8 h;			245 230	℃ ℃
			Please refer to customer information file No. 7 for details.				



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ELECTRICAL CHARACTERISTICS

ltem No.	Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Total	Device		1				
001	VCC	Permissible Supply Voltage		4		5.5	V
002	I(VCC)	Supply Current in VCC, dark	E() = 0 Tj = 27 °C		1.0	2	mA mA
003	I(VCC)	Supply Current in VCC	$\lambda_{\text{LED}} = \lambda pk, E() = 0.1 \text{ mW/cm}^2$ Tj = 27 °C		1.5	4	mA mA
004	Vc()hi	Clamp-Voltage hi at all pins	I() = 4 mA			11	V
005	Vc()lo	Clamp-Voltage lo at all pins	I() = -4 mA	-1.2		-0.3	V
Photo	sensors	-					u
101	E()mxr	Permissible Irradiance	$\lambda_{\text{LED}} = \lambda pk$			0.2	mW/ cm ²
102	Aph()	Radiant Sensitive Area	0.8 mm x 0.3 mm per sensor		0.24		mm ²
103	λ ar	Spectral Application Range	Se(λ ar) = 0.25 x S(λ)max see Figure 1	400		950	nm
104	λpk	Peak Sensitivity Wavelength	see Figure 1		680		nm
105	$S(\lambda)$	Spectral Sensitivity	$\lambda_{\text{LED}} = \lambda pk$		0.45		A/W
Photo	current Am	plifiers	1				u
201	lph()	Permissible Photocurrent Operating Range	per sensor	0		200	nA
202	η()r	Photo Sensitivity (light-to-voltage conversion ratio)	$\lambda_{\text{LED}} = 740 \text{nm}$	60		120	A/W
203	CR()	Photocurrent Gain	CR() = lout() / lph()	150	200	250	
204	fc()hi	Cut-off Frequency (-3 dB)		150	200		kHz
205	⊿lout()m	Channel Matching	deviation from mean value	-15		+15	%
206	⊿lout()m	Channel Cross Talk	only one photosensor illuminated at the same time		0		%
Curre	nt Source C	Dutputs	·				
301	Vout()	Permissible Output Voltage (Operating Range)		1		VCC - 1.5	V
302	lout()	Permissible Output Current	Vout() = 1 V VCC - 1.5 V VCC = 4.55.5 V, Vout() = 1 V VCC - 2 V	-50 -200			μΑ μΑ
303	tr(), tf()	Output Current Rise/Fall Time	lph: 0 \rightarrow 100 nA, 1T settling (63%); Vout() = constant CL = 30 pF, RL() = 10 k Ω		0.7 0.8		µs µs
304	lout()0	Output Dark Current		-0.6		+0.6	μA

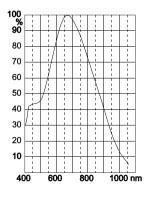


Figure 1: Relative spectral response

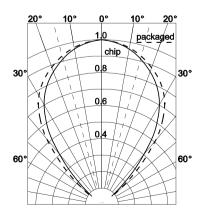


Figure 2: Typical directional characteristics



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APPLICATION CIRCUITS

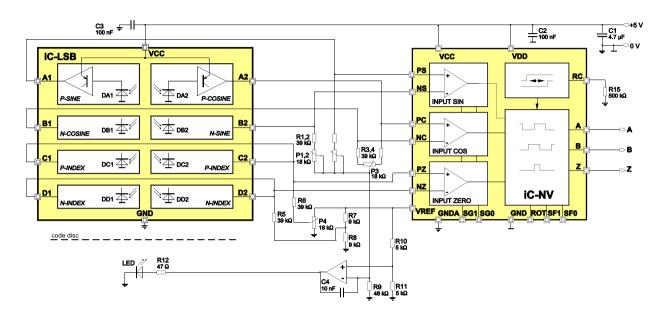


Figure 3: Optical encoder application example. Here, the sine-to-digital converter iC-NV is employed to output spike-free encoder quadrature signals featuring a minimum transition distance.

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ORDERING INFORMATION

Туре	Package	Options	Order Designation
iC-LSB	-		iC-LSB chip
	14-pin optoBGA 6.2 mm x 5.2 mm	glass lid	iC-LSB oBGA LS2C
	14-pin optoBGA 6.2 mm x 5.2 mm	on-chip reticle	iC-LSB oBGA LS2C-LSBxR

For technical support, information about prices and terms of delivery please contact:

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